

10 9 8 7 6 5 4 3 2 1

NOTES :

1. MATERIAL :

HOUSING : (a) HIGH TEMP. NYLON ,GLASS FIBER FILLED,UL94V-0, COLOR: BLACK,
(b) POLYESTER , GLASS FIBER FILLED,UL94V-0, COLOR: WHITE,

TERMINAL : PHOSPHOR BRONZE
METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL :

CONTACT AREA : (a) GOLD FLASH,

(b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM,
/0.76 MICROMETER MINIMUM.

SOLDER TAIL :

PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
/1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.

/1.27 MICROMETER MINIMUM.

METAL SHELL :

PURE TIN(Sn) , THICKNESS= 50 MICROINCH MINIMUM.
/1.27 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni) , THICKNESS= 50 MICROINCH MINIMUM.

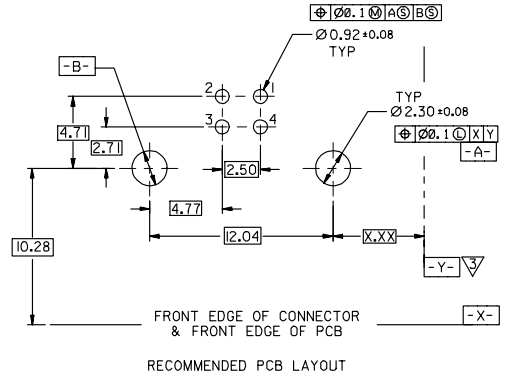
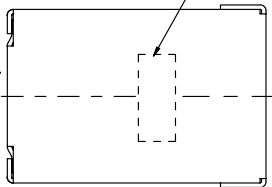
/1.27 MICROMETER MINIMUM.

▽ DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER

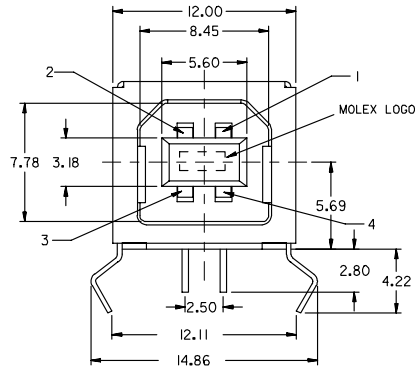
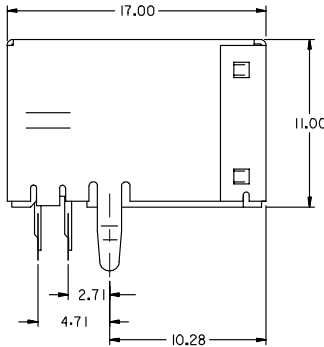
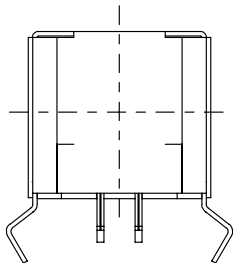
RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



FRONT EDGE OF CONNECTOR & FRONT EDGE OF PCB
RECOMMENDED PCB LAYOUT



PART NUMBER LEGEND:

67068- * * 0 *

8 : BLACK HOUSING
9 : WHITE HOUSING

0 : TRAY PACKAGING
1 : TUBE PACKAGING

0 : GOLD FLASH
1 : 0.76 MICROMETER/30 MICROINCH GOLD
KINK TYPE BOARD LOCK

NEW RELEASE EC NO. SH2005-0142 DRAWN: DAVID HU 2004/11/5 CHKD: HARVEY 2004/11/25 APPR: YITAP 2004/11/25	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.25 ± ---	1 PLACE ± 0.25 ± ---	ANGULAR ± 3 °	DRAWN BY DAVID HU	DATE 2004/11/05
A	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE NOTES		MATERIAL NO. DOCUMENT NO.		MOLEX INCORPORATED
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SD-67068-003		SHEET NO. 1 OF 4

9 8 7 6 5 4 3 2 1

ENG. NO SDA-67068-0000

EDP NO.

SIMILAR ITEM

CAD FILE : _S6706802_

DO NOT SCALE DRAWING

NOTES :

1. MATERIAL :

HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,

TERMINAL : PHOSPHOR BRONZE
METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL : (a) GOLD FLASH,
CONTACT AREA : (b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM,
/0.76 MICROMETER MINIMUM.

SOLDER TAIL : PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM,
/1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM,
/1.27 MICROMETER MINIMUM.

METAL SHELL : PURE TIN(Sn) THICKNESS= 50 MICROINCH MINIMUM,
/1.27 MICROMETER MINIMUM.

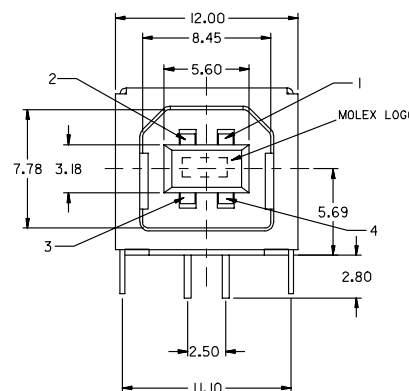
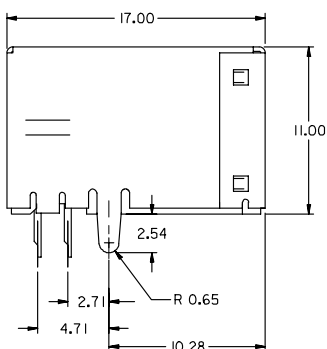
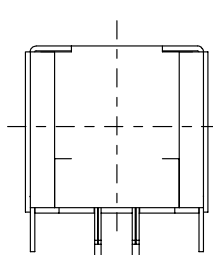
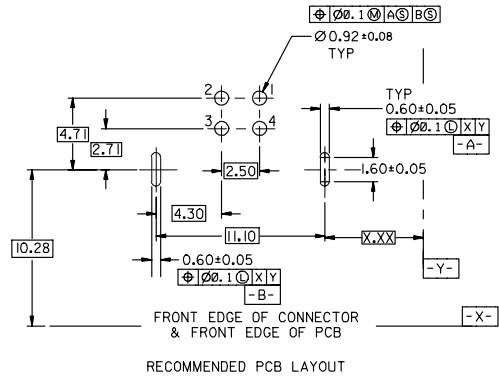
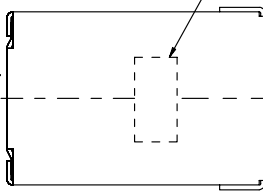
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM,
/1.27 MICROMETER MINIMUM.

3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER

RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



PART NUMBER LEGEND:

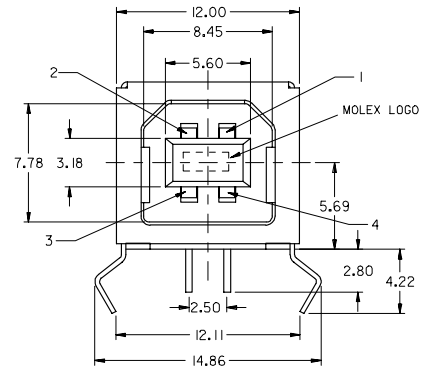
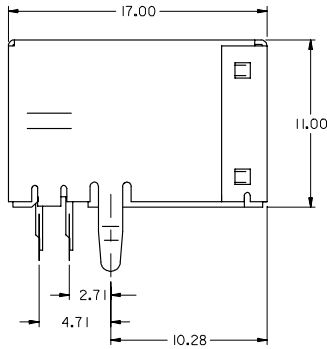
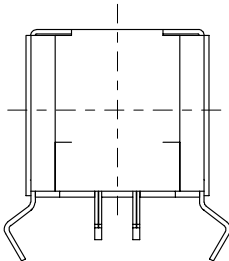
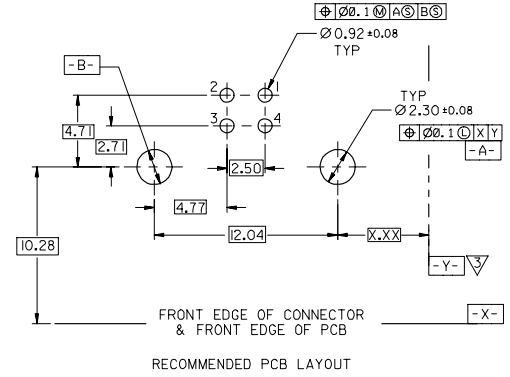
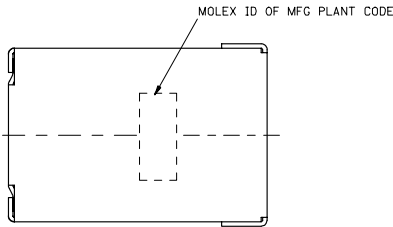
67068- 7051

				MATERIAL : SEE NOTES		MOLEX TAIWAN LTD.	
				FINISH : SEE NOTES		SHEET 4 OF 4	
				WIRE RANGE :		GENERAL TOLERANCES	
				INS. RANGE :		ANGLE : ± 3° DIM : ± .25/.010	
A NEW RELEASE FOR LEAD-FREE				DAVID HJ 2006/11/5		ENG. NO.: SD-67068-003	
LTR REVISION RECORD ECN DR DATE				DRAWN BY 2006/11/5 DAVID HJ		REV A	
REVISE ONLY ON CAD SYSTEM				APPR'D BY		TITLE : HIGH TEMPSUB B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE)	
				SCALE 4 : 1			

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX (FEMLE) AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

MXT, Sg - 13

NOTES:
 1.MATERIAL:
 HOUSING:
 (a)HIGH TEMP,NYLON,GLASS FIBRE FILLED,UL94V-0,COLOR: 8#BLACK
 (b)POLYESTER(PBT),30% GLASS FIBER FILLED,UL94V-0,COLOR: 9#WHITE
 TERMINAL: PHOSPHOR BRONZE
 METAL SHELL: COPPER ALLOY
 2.PLATING:
 TERMINAL:
 (c)GOLD FLASH ON CONTACT AREA,75 MICRONCH MINIMUM PURE TIN(Sn)
 ON SOLDER TAIL,UNDER 50 MICRONCH MINIMUM NICKEL(Ni) PLATE.
 (d)30 MICRONCH MINIMUM GOLD(Au) ON CONTACT AREA,75 MICRONCH
 MINIMUM PURE TIN(Sn) ON SOLDER TAIL,UNDER 50 MICRONCH
 MINIMUM NICKEL(Ni) PLATE.
 (e)GOLD FLASH ON CONTACT AREA,75 MICRONCH MINIMUM MATTE TIN(Sn)
 ON SOLDER TAIL,UNDER 50 MICRONCH MINIMUM NICKEL(Ni) PLATE.
 (f)30 MICRONCH MINIMUM GOLD(Au) ON CONTACT AREA,75 MICRONCH
 MINIMUM MATTE TIN(Sn) ON SOLDER TAIL,UNDER 50 MICRONCH
 MINIMUM NICKEL(Ni) PLATE.
 METAL SHELL:
 (g)50 MICRONCH MINIMUM PURE TIN(Sn),UNDER 50 MICRONCH MINIMUM
 NICKEL(Ni) PLATE.
 (h)50 MICRONCH MINIMUM MATTE TIN(Sn),UNDER 50 MICRONCH MINIMUM
 NICKEL(Ni) PLATE.
 3.DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.
 RECOMMENDED PCB THICKNESS : 1.60±0.05
 4.PRODUCT SPECIFICATION : REFER TO PS-67998-0000



P/N	HOUSING COLOR	PLATING
67068-8000	BLACK	GOLD FLASH SEE NOTES[2-(c),2-(g)]
67068-8001	BLACK	30MICRONCH Au SEE NOTES[2-(d),2-(g)]
67068-9000	WHITE	GOLD FLASH SEE NOTES[2-(c),2-(g)]
67068-9001	WHITE	30MICRONCH Au SEE NOTES[2-(d),2-(g)]
67068-8012	BLACK	30MICRONCH Au SEE NOTES[2-(f),2-(h)]
67068-8013	BLACK	GOLD FLASH SEE NOTES[2-(e),2-(h)]

REVISED EC NO. SH2007-0468 2007/01/19 DRW:HYH01 CHKC:WANG 2007/01/19 APPR: JIN-CHEN 2007/01/26	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES	± ---	± ---	DRAWN BY DAVID HU	DATE 2004/11/05	TITLE USB B TYPE CONNECTOR LEAD-FREE			
		3 PLACES	± ---	± ---	CHECKED BY HARVEY	DATE 2004/11/05				
		2 PLACES	± 0.25	± 0.10	APPROVED BY DATE		MATERIAL NO. SEE NOTES			
1 PLACE	± 0.25	± 0.10	ANGULAR ± 3°		DOCUMENT NO. SD-67068-004		SHEET NO. 1 OF 1			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						